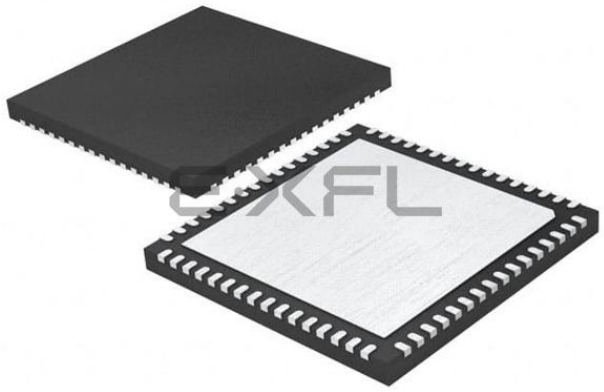
Microchip Technology - PIC32MX420F032H-40V/MR Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx420f032h-40v-mr

PIC32MX3XX/4XX

High-Performance, General Purpose and USB 32-bit Flash Microcontrollers

High-Performance 32-bit RISC CPU:

- MIPS32® M4K® 32-bit core with 5-stage pipeline
- 80 MHz maximum frequency
- 1.56 DMIPS/MHz (Dhrystone 2.1) performance at 0 wait state Flash access
- Single-cycle multiply and high-performance divide unit
- MIPS16e® mode for up to 40% smaller code size
- Two sets of 32 core register files (32-bit) to reduce interrupt latency
- Prefetch Cache module to speed execution from Flash

Microcontroller Features:

- Operating temperature range of -40ºC to +105ºC
- Operating voltage range of 2.3V to 3.6V
- 32K to 512K Flash memory (plus an additional 12 KB of boot Flash)
- 8K to 32K SRAM memory
- Pin-compatible with most PIC24/dsPIC® DSC devices
- Multiple power management modes
- Multiple interrupt vectors with individually programmable priority
- Fail-Safe Clock Monitor Mode
- Configurable Watchdog Timer with on-chip Low-Power RC Oscillator for reliable operation

Peripheral Features:

- Atomic SET, CLEAR and INVERT operation on select peripheral registers
- Up to 4-channel hardware DMA with automatic data size detection
- USB 2.0-compliant full-speed device and On-The-Go (OTG) controller
- USB has a dedicated DMA channel
- 3 MHz to 25 MHz crystal oscillator
- Internal 8 MHz and 32 kHz oscillators
- Separate PLLs for CPU and USB clocks
- Two I^2C™ modules
- Two UART modules with:
  - RS-232, RS-485 and LIN support
  - IrDA® with on-chip hardware encoder and decoder
- Up to two SPI modules
- Parallel Master and Slave Port (PMP/PSP) with 8-bit and 16-bit data and up to 16 address lines
- Hardware Real-Time Clock and Calendar (RTCC)
- Five 16-bit Timers/Counters (two 16-bit pairs combine to create two 32-bit timers)
- Five capture inputs
- Five compare/PWM outputs
- Five external interrupt pins
- High-Speed I/O pins capable of toggling at up to 80 MHz
- High-current sink/source (18 mA/18 mA) on all I/O pins
- Configurable open-drain output on digital I/O pins

Debug Features:

- Two programming and debugging Interfaces:
  - 2-wire interface with unintrusive access and real-time data exchange with application
  - 4-wire MIPS® standard enhanced JTAG interface
- Unintrusive hardware-based instruction trace
- IEEE Standard 1149.2-compatible (JTAG) boundary scan

Analog Features:

- Up to 16-channel 10-bit Analog-to-Digital Converter:
  - 1000 ksps conversion rate
  - Conversion available during Sleep, Idle
- Two Analog Comparators

Pin Diagrams (Continued)

121-Pin XBGA(1)

● = Pins are up to 5V tolerant

PIC32MX440F128L
PIC32MX460F256L
PIC32MX460F512L

	1	2	3	4	5	6	7	8	9	10	11
A	RE4	RE3	RG13	RE0	RG0	RF1	ENVREG	VSS	RD12	RD2	RD1
B	NC	RG15	RE2	RE1	RA7	RF0	VCORE/ VCAP	RD5	RD3	VSS	RC14
C	RE6	VDD	RG12	RG14	RA6	NC	RD7	RD4	VDD	RC13	RD11
D	RC1	RE7	RE5	VSS	VSS	NC	RD6	RD13	RD0	NC	RD10
E	RC4	RC3	RG6	RC2	VDD	RG1	VSS	RA15	RD8	RD9	RA14
F	$\overline{\text{MCLR}}$	RG8	RG9	RG7	VSS	NC	NC	VDD	RC12	VSS	RC15
G	RE8	RE9	RA0	NC	VDD	VSS	VSS	NC	RA5	RA3	RA4
H	RB5	RB4	VSS	VDD	NC	VDD	NC	VBUS	VUSB	RG2	RA2
J	RB3	RB2	RB7	AVDD	RB11	RA1	RB12	NC	NC	RF8	RG3
K	RB1	RB0	RA10	RB8	NC	RF12	RB14	VDD	RD15	RF3	RF2
L	RB6	RA9	AVSS	RB9	RB10	RF13	RB13	RB15	RD14	RF4	RF5

Note 1: Refer to Table 4 for full pin names.

TABLE 4-16: DMA CHANNELS 0-3 REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY(1) (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3160	DCH1DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3170	DCH1SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
3180	DCH1DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
3190	DCH1SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSPTR<7:0>								0000
31A0	DCH1DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDPTR<7:0>								0000
31B0	DCH1CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCSIZ<7:0>								0000
31C0	DCH1CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCPTR<7:0>								0000
31D0	DCH1DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
31E0	DCH2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
31F0	DCH2ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3200	DCH2INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3210	DCH2SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
3220	DCH2DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3230	DCH2SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
3240	DCH2DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
3250	DCH2SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSPTR<7:0>								0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers except DCHxSPTR, DCHxDPTR and DCHxCPTR have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-29: PORTF REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L AND PIC32MX360F512L DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TRISF13	TRISF12	—	—	—	TRISF8	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	31FF
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	RF13	RF12	—	—	—	RF8	RF7	RF6	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	LATF13	LATF12	—	—	—	LATF8	LATF7	LATF6	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	ODCF13	ODCF12	—	—	—	ODCF8	ODCF7	ODCF6	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-30: PORTF REGISTERS MAP FOR PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TRISF13	TRISF12	—	—	—	TRISF8	—	—	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	313F
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	RF13	RF12	—	—	—	RF8	—	—	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	LATF13	LATF12	—	—	—	LATF8	—	—	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	ODCF13	ODCF12	—	—	—	ODCF8	—	—	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-40: RTCC REGISTERS MAP(1)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0200	RTCCON	31:16	—	—	—	—	—	—	CAL<11:0>										0000
		15:0	ON	—	SIDL	—	—	—	—	—	RTSECSEL	RTCCLKON	—	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	0000
0210	RTCALRM	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ALRMEN	CHIME	PIV	ALRMSYNC	AMASK<3:0>				ARPT<7:0>								0000
0220	RTCTIME	31:16	HR10<3:0>				HR01<3:0>				MIN10<3:0>				MIN01<3:0>				xxxx
		15:0	SEC10<3:0>				SEC01<3:0>				—	—	—	—	—	—	—	—	xx00
0230	RTCDATE	31:16	YEAR10<3:0>				YEAR01<3:0>				MONTH10<3:0>				MONTH01<3:0>				xxxx
		15:0	DAY10<3:0>				DAY01<3:0>				—	—	—	—	WDAY01<3:0>				xx0x
0240	ALRMTIME	31:16	MIN10<3:0>				MIN01<3:0>				MIN10<3:0>				MIN01<3:0>				xxxx
		15:0	SEC10<3:0>				SEC01<3:0>				—	—	—	—	—	—	—	—	xx00
0250	ALRMDATE	31:16	—	—	—	—	—	—	—	—	MONTH10<3:0>				MONTH01<3:0>				00xx
		15:0	DAY10<3:0>				DAY01<3:0>				—	—	—	—	WDAY01<3:0>				xx0x

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-41: DEVCFG: DEVICE CONFIGURATION WORD SUMMARY

Virtual Address (BFC0_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2FF0	DEVCFG3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
		15:0	USERID15	USERID14	USERID13	USERID12	USERID11	USERID10	USERID9	USERID8	USERID7	USERID6	USERID5	USERID4	USERID3	USERID2	USERID1	USERID0	xxxx
2FF4	DEVCFG2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	FPLLODIV<2:0>			xxxx
		15:0	UPLLEN(1)	—	—	—	—	UPLLIDIV<2:0>(1)			—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>			xxxx
2FF8	DEVCFG1	31:16	—	—	—	—	—	—	—	—	FWDTEN	—	—	WDTPS<4:0>					xxxx
		15:0	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>		IESO	—	FSOSCEN	—	—	FNOSC<2:0>			xxxx
2FFC	DEVCFG0	31:16	—	—	—	CP	—	—	—	BWP	—	—	—	—	PWP19	PWP18	PWP17	PWP16	xxxx
		15:0	PWP15	PWP14	PWP13	PWP12	—	—	—	—	—	—	—	—	ICESEL	—	DEBUG<1:0>		xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: These bits are only available on PIC32MX4XX devices.

6.0 RESETS

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 7. "Resets"** (DS61118) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

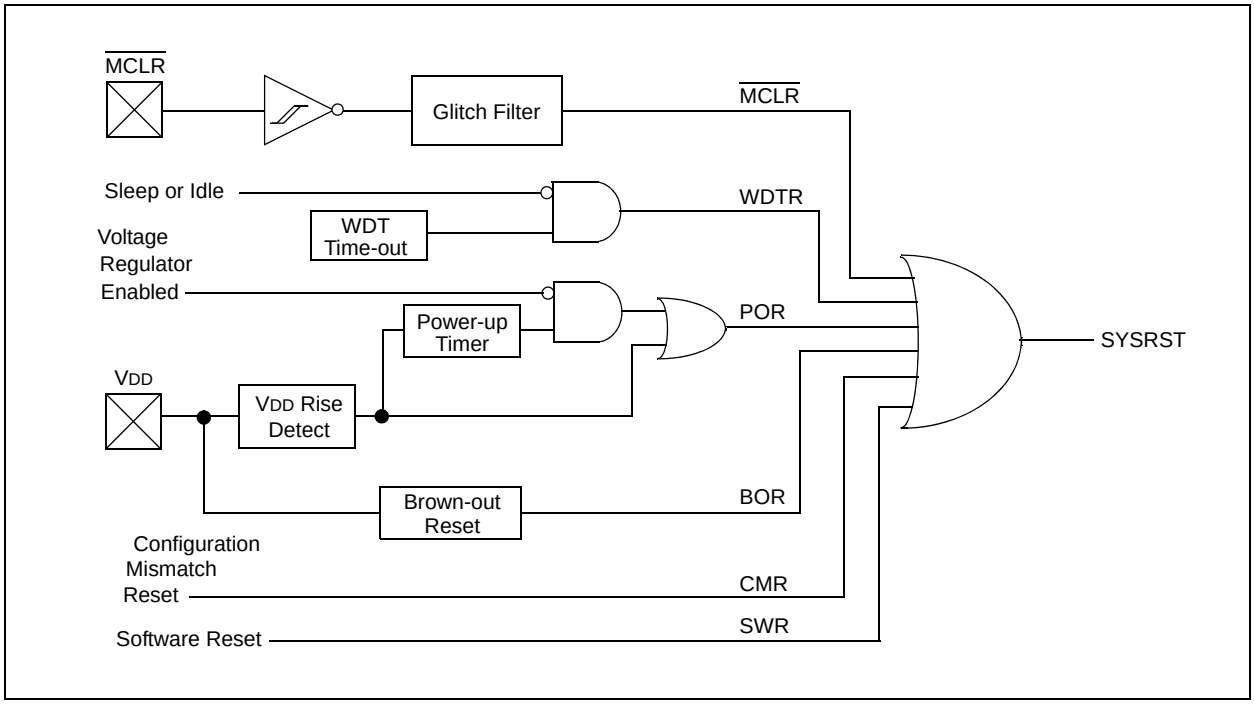
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Reset module combines all Reset sources and controls the device Master Reset signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- $\overline{\text{MCLR}}$: Master Clear Reset Pin
- SWR: Software Reset
- WDTR: Watchdog Timer Reset
- BOR: Brown-out Reset
- CMR: Configuration Mismatch Reset

A simplified block diagram of the Reset module is illustrated in Figure 6-1.

FIGURE 6-1: SYSTEM RESET BLOCK DIAGRAM



11.0 USB ON-THE-GO (OTG)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 27. "USB On-The-Go (OTG)"** (DS61126) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Universal Serial Bus (USB) module contains analog and digital components to provide a USB 2.0 full-speed and low-speed embedded host, full-speed device, or OTG implementation with a minimum of external components. This module in Host mode is intended for use as an embedded host and therefore does not implement a UHCI or OHCI controller.

The USB module consists of the clock generator, the USB voltage comparators, the transceiver, the Serial Interface Engine (SIE), a dedicated USB DMA controller, pull-up and pull-down resistors, and the register interface. A block diagram of the PIC32MX USB OTG module is presented in Figure 11-1.

The clock generator provides the 48 MHz clock required for USB full-speed and low-speed communication. The voltage comparators monitor the voltage on the VBUS pin to determine the state of the bus. The transceiver provides the analog translation between the USB bus and the digital logic. The SIE is a state machine that transfers data to and from the endpoint buffers, and generates the hardware protocol for data transfers. The USB DMA controller transfers data between the data buffers in RAM and the SIE. The integrated pull-up and pull-down resistors eliminate the need for external signaling components. The register interface allows the CPU to configure and communicate with the module.

The PIC32MX USB module includes the following features:

- USB Full-Speed Support for Host and Device
- Low-Speed Host Support
- USB OTG Support
- Integrated Signaling Resistors
- Integrated Analog Comparators for VBUS Monitoring
- Integrated USB Transceiver
- Transaction Handshaking Performed by Hardware
- Endpoint Buffering Anywhere in System RAM
- Integrated DMA to Access System RAM and Flash

Note: The implementation and use of the USB specifications, as well as other third-party specifications or technologies, may require licensing; including, but not limited to, USB Implementers Forum, Inc. (also referred to as USB-IF). The user is fully responsible for investigating and satisfying any applicable licensing obligations.

12.0 I/O PORTS

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "I/O Ports"** (DS61120) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

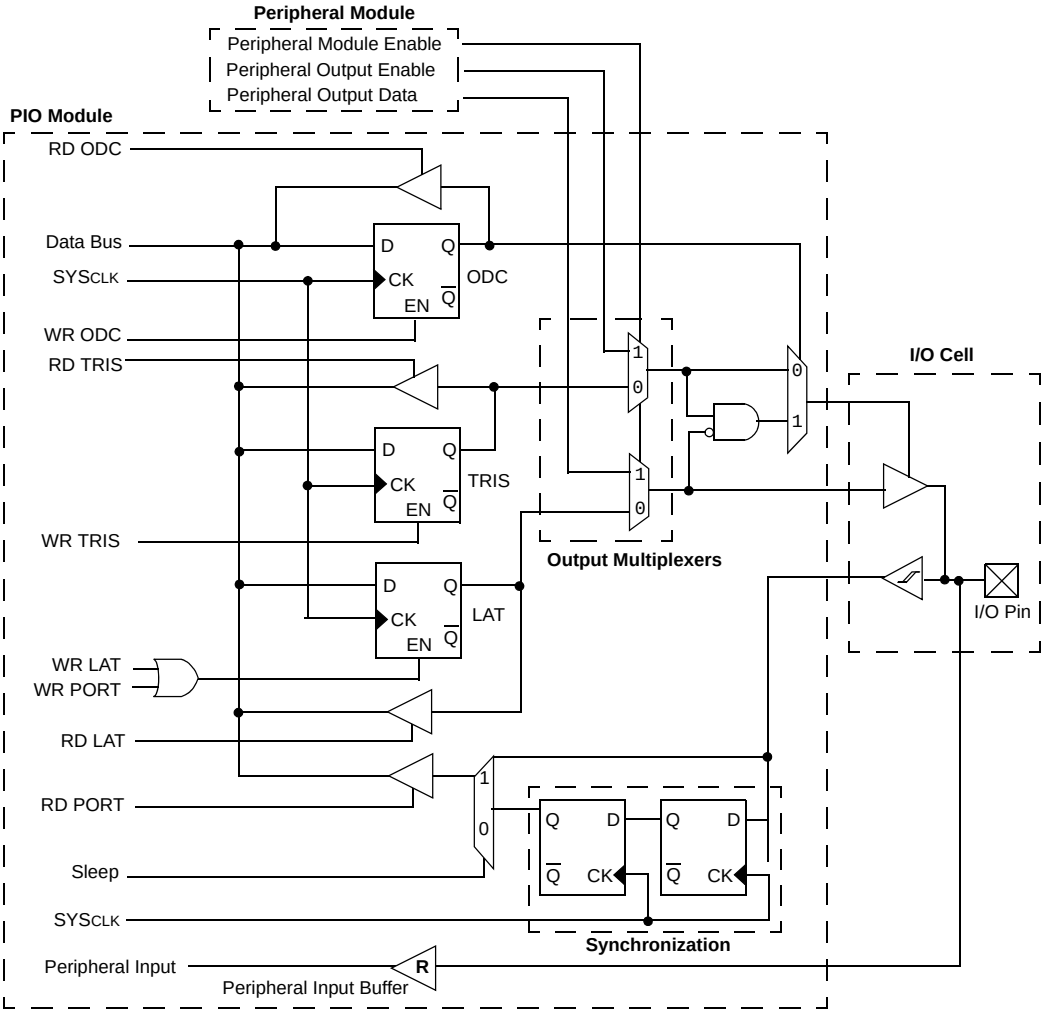
General purpose I/O pins are the simplest of peripherals. They allow the PIC® MCU to monitor and control other devices. To add flexibility and functionality, some pins are multiplexed with alternate function(s). These functions depend on which peripheral features are on the device. In general, when a peripheral is functioning, that pin may not be used as a general purpose I/O pin.

Following are some of the key features of this module:

- Individual Output Pin Open-drain Enable/Disable
- Individual Input Pin Weak Pull-up Enable/Disable
- Monitor Selective Inputs and Generate Interrupt when Change in Pin State is Detected
- Operation during CPU Sleep and Idle modes
- Fast Bit Manipulation using CLR, SET and INV Registers

Figure 12-1 illustrates a block diagram of a typical multiplexed I/O port.

FIGURE 12-1: BLOCK DIAGRAM OF A TYPICAL MULTIPLEXED PORT STRUCTURE



Legend: R = Peripheral input buffer types may vary. Refer to Table 1-1 for peripheral details.

Note: This block diagram is a general representation of a shared port/peripheral structure for illustration purposes only. The actual structure for any specific port/peripheral combination may be different than it is shown here.

12.1 Parallel I/O (PIO) Ports

All port pins have three registers (TRIS, LAT and PORT) that are directly associated with their operation.

TRIS is a data direction or tri-state control register that determines whether a digital pin is an input or an output. Setting a TRISx register bit = 1 configures the corresponding I/O pin as an input; setting a TRISx register bit = 0 configures the corresponding I/O pin as an output. All port I/O pins are defined as inputs after a device Reset. Certain I/O pins are shared with analog peripherals and default to analog inputs after a device Reset.

PORT is a register used to read the current state of the signal applied to the port I/O pins. Writing to a PORTx register performs a write to the port's latch, LATx register, latching the data to the port's I/O pins.

LAT is a register used to write data to the port I/O pins. The LATx latch register holds the data written to either the LATx or PORTx registers. Reading the LATx latch register reads the last value written to the corresponding port or latch register.

Not all port I/O pins are implemented on some devices, therefore, the corresponding PORTx, LATx and TRISx register bits will read as zeros.

12.1.1 CLR, SET AND INV REGISTERS

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

Note:	Using a PORTxINV register to toggle a bit is recommended because the operation is performed in hardware atomically, using fewer instructions as compared to the traditional read-modify-write method shown below: PORTC ^= 0x0001;

12.1.2 DIGITAL INPUTS

Pins are configured as digital inputs by setting the corresponding TRIS register bits = 1. When configured as inputs, they are either TTL buffers or Schmitt Triggers. Several digital pins share functionality with analog inputs and default to the analog inputs at POR. Setting the corresponding bit in the AD1PCFG register = 1 enables the pin as a digital pin.

The maximum input voltage allowed on the input pins is the same as the maximum VIH specification. Refer to **Section 29.0 "Electrical Characteristics"** for VIH specification details.

Note:	Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

12.1.3 ANALOG INPUTS

Certain pins can be configured as analog inputs used by the ADC and Comparator modules. Setting the corresponding bits in the AD1PCFG register = 0 enables the pin as an analog input pin and must have the corresponding TRIS bit set = 1 (input). If the TRIS bit is cleared = 0 (output), the digital output level (VOH or VOL) will be converted. Any time a port I/O pin is configured as analog, its digital input is disabled and the corresponding PORTx register bit will read '0'. The AD1PCFG Register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

12.1.4 DIGITAL OUTPUTS

Pins are configured as digital outputs by setting the corresponding TRIS register bits = 0. When configured as digital outputs, these pins are CMOS drivers or can be configured as open drain outputs by setting the corresponding bits in the ODCx Open-Drain Configuration register.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

12.1.5 ANALOG OUTPUTS

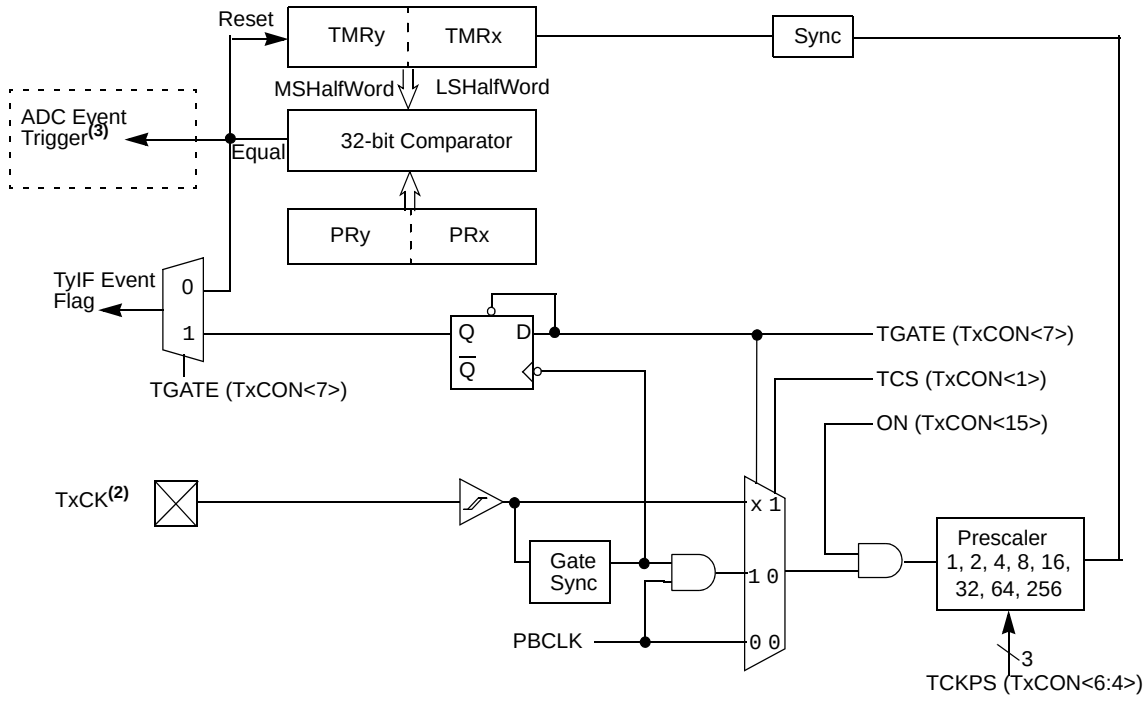
Certain pins can be configured as analog outputs, such as the CVREF output voltage used by the comparator module. Configuring the Comparator Reference module to provide this output will present the analog output voltage on the pin, independent of the TRIS register setting for the corresponding pin.

12.1.6 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports (CNx) allows devices to generate interrupt requests in response to change of state on selected pin.

Each CNx pin also has a weak pull-up, which acts as a current source connected to the pin. The pull-ups are enabled by setting corresponding bit in CNPUE register.

FIGURE 14-2: TIMER2/3, 4/5 BLOCK DIAGRAM (32-BIT)



Note 1: In this diagram, the use of 'x' in registers TxCON, TMRx, PRx and TxCK refers to either Timer2 or Timer4; the use of 'y' in registers TyCON, TMRy, PRy and TyIF refers to either Timer3 or Timer5.

2: TxCK pins are not available on 64-pin devices.

3: ADC event trigger is available only on Timer2/3 pair.

18.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. "Inter-Integrated Circuit (I^2C™)"** (DS61116) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard. Figure 18-1 illustrates the I^2C module block diagram.

The PIC32MX3XX/4XX devices have up to two I^2C interface modules, denoted as I2C1 and I2C2. Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module, 'I2Cx' (x = 1 or 2), offers the following key features:

- I^2C Interface Supporting both Master and Slave Operation.
- I^2C Slave Mode Supports 7 and 10-bit Address.
- I^2C Master Mode Supports 7 and 10-bit Address.
- I^2C Port allows Bidirectional Transfers between Master and Slaves.
- Serial Clock Synchronization for I^2C Port can be used as a Handshake Mechanism to Suspend and Resume Serial Transfer (SCLREL control).
- I^2C Supports Multi-master Operation; Detects Bus Collision and Arbitrates Accordingly.
- Provides Support for Address Bit Masking.

20.0 PARALLEL MASTER PORT (PMP)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 13. "Parallel Master Port (PMP)"** (DS61128) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

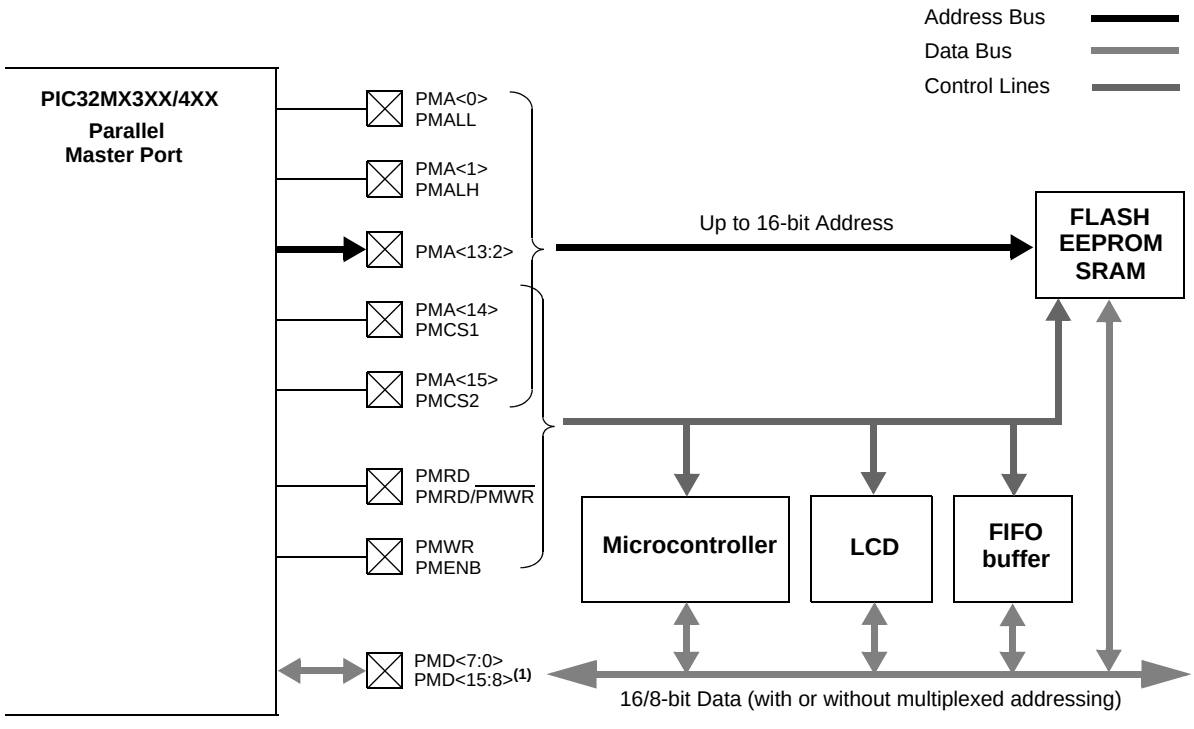
The PMP is a parallel 8-bit/16-bit input/output module specifically designed to communicate with a wide variety of parallel devices, such as communications peripherals, LCDs, external memory devices and microcontrollers. Because the interface to parallel peripherals varies significantly, the PMP module is highly configurable.

Key features of the PMP module include:

- 8-bit,16-bit interface
- Up to 16 programmable address lines
- Up to two Chip Select lines
- Programmable strobe options
  - Individual read and write strobes, or
  - Read/write strobe with enable strobe
- Address auto-increment/auto-decrement
- Programmable address/data multiplexing
- Programmable polarity on control signals
- Parallel Slave Port support
  - Legacy addressable
  - Address support
  - 4-byte deep auto-incrementing buffer
- Programmable Wait states
- Operate during CPU Sleep and Idle modes
- Fast bit manipulation using CLR, SET and INV registers
- Freeze option for in-circuit debugging

Note: On 64-pin devices, data pins PMD<15:8> are not available.

FIGURE 20-1: PMP MODULE PINOUT AND CONNECTIONS TO EXTERNAL DEVICES



Note 1: On 64-pin devices, data pins PMD<15:8> are not available in 16-bit Master modes.

REGISTER 26-3: DEVCFG2: DEVICE CONFIGURATION WORD 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	FPLLODIV<2:0>		
15:8	R/P	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	UPLLEN	—	—	—	—	UPLLIDIV<2:0>		
7:0	r-1	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>		

Legend:			
R = Readable bit	W = Writable bit	P = Programmable bit	r = Reserved bit
U = Unimplemented bit	-n = Bit Value at POR: (‘0’, ‘1’, x = Unknown)		

bit 31-19 **Reserved:** Write ‘1’

bit 18-16 **FPLLODIV<2:0>:** Default Postscaler for PLL bits
- 111 = PLL output divided by 256
- 110 = PLL output divided by 64
- 101 = PLL output divided by 32
- 100 = PLL output divided by 16
- 011 = PLL output divided by 8
- 010 = PLL output divided by 4
- 001 = PLL output divided by 2
- 000 = PLL output divided by 1

bit 15 **UPLLEN:** USB PLL Enable bit
- 1 = Disable and bypass USB PLL
- 0 = Enable USB PLL

bit 14-11 **Reserved:** Write ‘1’

bit 10-8 **UPLLIDIV<2:0>:** PLL Input Divider bits
- 111 = 12x divider
- 110 = 10x divider
- 101 = 6x divider
- 100 = 5x divider
- 011 = 4x divider
- 010 = 3x divider
- 010 = 3x divider
- 001 = 2x divider
- 000 = 1x divider

bit 7 **Reserved:** Write ‘1’

bit 6-4 **FPLLMUL<2:0>:** PLL Multiplier bits
- 111 = 24x multiplier
- 110 = 21x multiplier
- 101 = 20x multiplier
- 100 = 19x multiplier
- 011 = 18x multiplier
- 010 = 17x multiplier
- 001 = 16x multiplier
- 000 = 15x multiplier

bit 3 **Reserved:** Write ‘1’

bit 2-0 **FPLLIDIV<2:0>:** PLL Input Divider bits
- 111 = 12x divider
- 110 = 10x divider
- 101 = 6x divider
- 100 = 5x divider
- 011 = 4x divider
- 010 = 3x divider
- 001 = 2x divider
- 000 = 1x divider

REGISTER 26-6: DDPCON: DEBUG DATA PORT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-x	r-x	r-x	r-x	r-x	r-x	r-x	r-x
	—	—	—	—	—	—	—	—
23:16	r-x	r-x	r-x	r-x	r-x	r-x	r-x	r-x
	—	—	—	—	—	—	—	—
15:8	r-x	r-x	r-x	r-x	r-x	r-x	r-x	r-x
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	r-x	r-x
	DDPUSB	DDPU1	DDPU2	DDPSPI1	JTAGEN	TROEN	—	—

Legend:			
R = Readable bit	W = Writable bit	P = Programmable bit	r = Reserved bit
U = Unimplemented bit	-n = Bit Value at POR: (‘0’, ‘1’, x = Unknown)		

bit 31-8 **Reserved:** Write ‘0’; ignore read

bit 7 **DDPUSB:** Debug Data Port Enable for USB bit
1 = USB peripheral ignores USBFRZ (U1CNFG1<5>) setting
0 = USB peripheral follows USBFRZ setting

bit 6 **DDPU1:** Debug Data Port Enable for UART1 bit
1 = UART1 peripheral ignores FRZ (U1MODE<14>) setting
0 = UART1 peripheral follows FRZ setting

bit 5 **DDPU2:** Debug Data Port Enable for UART2 bit
1 = UART2 peripheral ignores FRZ (U2MODE<14>) setting
0 = UART2 peripheral follows FRZ setting

bit 4 **DDPSPI1:** Debug Data Port Enable for SPI1 bit
1 = SPI1 peripheral ignores FRZ (SPI1CON<14>) setting
0 = SPI1 peripheral follows FRZ setting

bit 3 **JTAGEN:** JTAG Port Enable bit
1 = Enable JTAG Port
0 = Disable JTAG Port

bit 2 **TROEN:** Trace Output Enable bit
1 = Enable Trace Port
0 = Disable Trace Port

bit 1-0 **Reserved:** Write ‘1’; ignore read

TABLE 29-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Typical(3)**	**Max.**	**Units**	**Conditions**			
Operating Current (IDD)(1,2)							
DC20	8.5	13	mA	Code executing from Flash	-40ºC, +25ºC, +85ºC	—	4 MHz
	9	15			+105ºC		
DC20c	4.0	—	mA	Code executing from SRAM	—		
DC21	23.5	32	mA	Code executing from Flash	—	—	20 MHz **(Note 4)**
DC21c	16.4	—	mA	Code executing from SRAM			
DC22	48	61	mA	Code executing from Flash	—	—	60 MHz **(Note 4)**
DC22c	45	—	mA	Code executing from SRAM			
DC23	55	75	mA	Code executing from Flash	-40ºC, +25ºC, +85ºC	2.3V	80 MHz
	60	100			+105ºC		
DC23c	55	—	mA	Code executing from SRAM	—	—	
DC24	—	100	µA	—	-40°C	2.3V	LPRC (31 kHz) **(Note 4)**
DC24a	—	130	µA	—	+25°C		
DC24b	—	670	µA	—	+85°C		
DC24c	—	850	µA	—	+105ºC		
DC25	94	—	µA	—	-40°C	3.3V	
DC25a	125	—	µA	—	+25°C		
DC25b	302	—	µA	—	+85°C		
DC25d	400	—	µA	—	+105ºC		
DC25c	71	—	µA	Code executing from SRAM	—	—	
DC26	—	110	µA	—	-40°C	3.6V	
DC26a	—	180	µA	—	+25°C		
DC26b	—	700	µA	—	+85°C		
DC26c	—	900	µA	—	+105ºC		

Note 1: A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type as well as temperature can have an impact on the current consumption.

2: The test conditions for IDD measurements are as follows: Oscillator mode = EC+PLL with OSC1 driven by external square wave from rail to rail and PBCLK divisor = 1:8. CPU, Program Flash and SRAM data memory are operational, Program Flash memory Wait states = 7, program cache and prefetch are disabled and SRAM data memory Wait states = 1. All peripheral modules are disabled (ON bit = 0). WDT and FSCM are disabled. All I/O pins are configured as inputs and pulled to VSS. MCLR = VDD.

3: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

4: This parameter is characterized, but not tested in manufacturing.

TABLE 29-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC40	7	30	µA	-40°C	2.3V	Base Power-Down Current **(Note 6)**
DC40a	24	30	µA	+25°C		
DC40b	205	300	µA	+85°C		
DC40h	450	900	µA	+105ºC		
DC40c	25	—	µA	+25°C	3.3V	Base Power-Down Current
DC40d	9	70	µA	-40°C	3.6V	Base Power-Down Current
DC40e	25	70	µA	+25°C		
DC40g	115	200(5)	µA	+70°C		
DC40f	200	400	µA	+85°C		
DC40i	470	1200	µA	+105ºC		
Module Differential Current						
DC41	—	10	µA	-40°C	2.3V	Watchdog Timer Current: ΔI_{WDT} **(Notes 3, 6)**
DC41a	—	10	µA	+25°C		
DC41b	—	10	µA	+85°C		
DC41g	—	12	µA	+105ºC		
DC41c	5	—	µA	+25°C	3.3V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC41d	—	10	µA	-40°C	3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC41e	—	10	µA	+25°C		
DC41f	—	12	µA	+85°C		
DC41h	—	15	µA	+105ºC		
DC42	—	10	µA	-40°C	2.3V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Notes 3, 6)**
DC42a	—	17	µA	+25°C		
DC42b	—	37	µA	+85°C		
DC42h	—	45	µA	+105ºC		
DC42c	23	—	µA	+25°C	3.3V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC42e	—	10	µA	-40°C	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC42f	—	30	µA	+25°C		
DC42g	—	44	µA	+85°C		
DC42i	—	44	µA	+105ºC		

Note 1: Base I_{PD} is measured with all digital peripheral modules disabled. All I/Os are configured as inputs and pulled low. WDT and FSCM are disabled.

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: Data is characterized at +70°C and not tested. Parameter is for design guidance only.

6: This parameter is characterized, but not tested in manufacturing.

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY(3)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	1000	—	—	E/W	—
D131	VPR	VDD for Read	VMIN	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	3.0	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	—
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	20	—	40	µs	—
D136	TRW	Row Write Cycle Time(2) (128 words per row)	3	4.5	—	ms	—
D137	TPE	Page Erase Cycle Time	20	—	—	ms	—
	TCE	Chip Erase Cycle Time	80	—	—	ms	—
D138	LVDstartup	Flash LVD Delay	—	—	6	µs	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the "*PIC32MX Flash Programming Specification*" (DS61145) for operating conditions during programming and erase cycles.

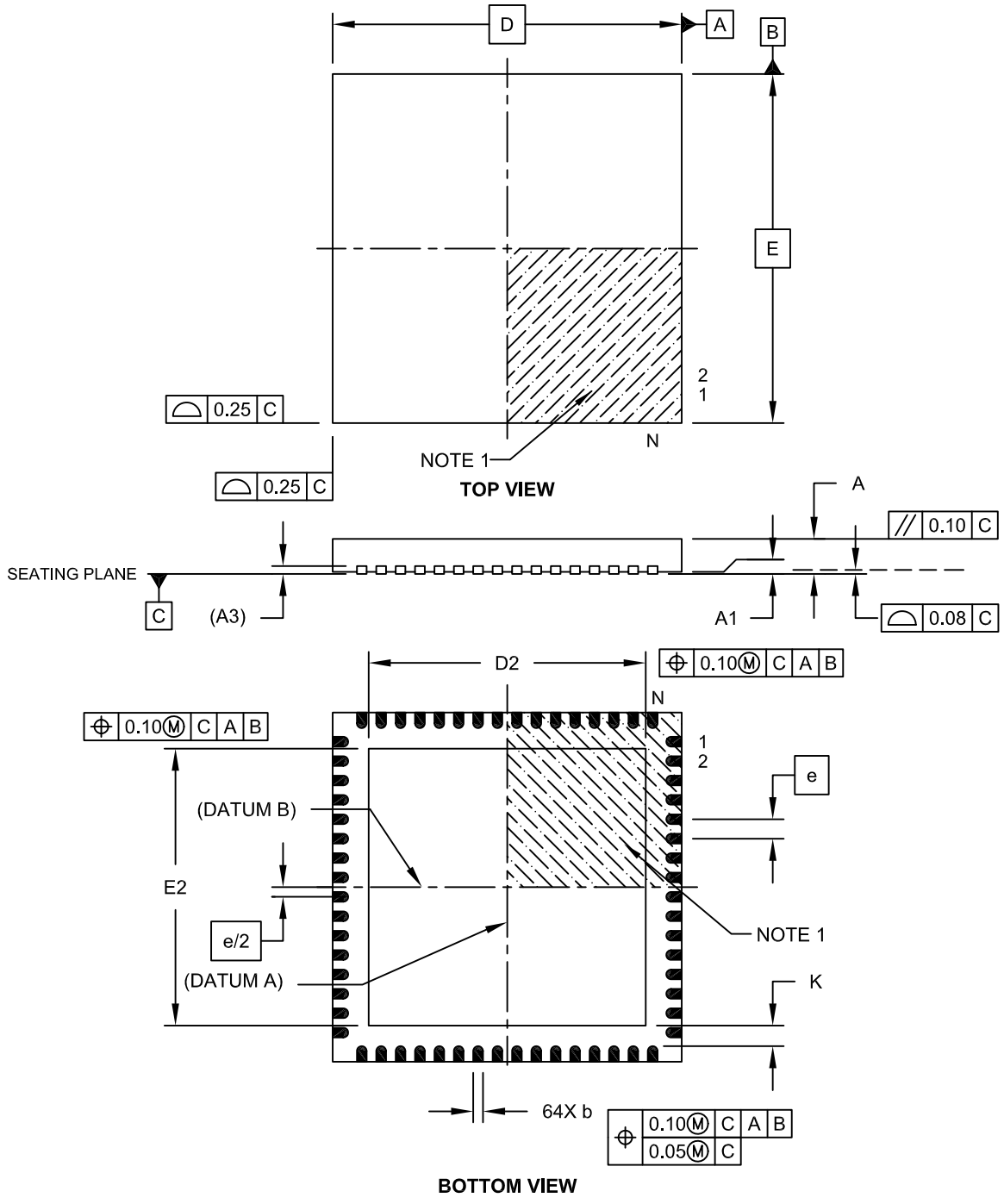
TABLE 29-12: PROGRAM FLASH MEMORY WAIT STATE CHARACTERISTICS

DC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp		
Required Flash wait states	**SYSCLK**	**Units**	**Comments**
0 Wait State	0 to 30	MHz	—
1 Wait State	31 to 60		
2 Wait States	61 to 80		

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 7.15 x 7.15 Exposed Pad [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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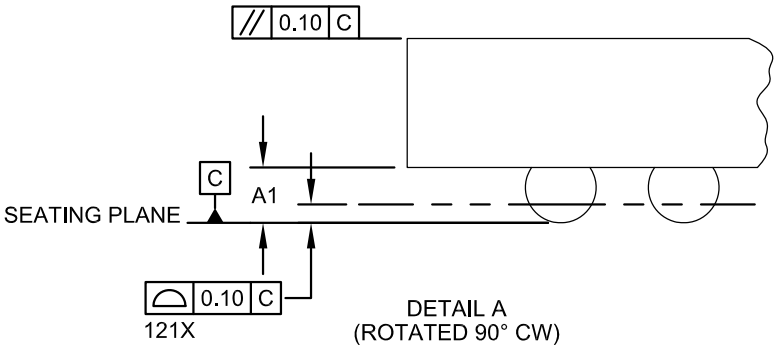
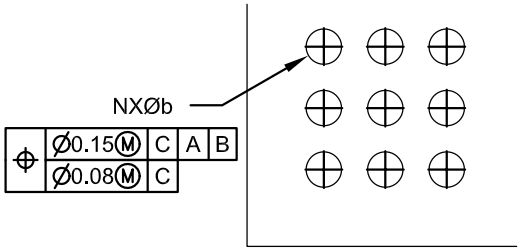
121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [XBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





DETAIL B

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Contacts	N		121	
Contact Pitch	e		0.80 BSC	
Overall Height	A	1.00	1.10	1.20
Standoff	A1	0.25	0.30	0.35
Molded Package Thickness	A2	0.55	0.60	0.65
Overall Width	E		10.00 BSC	
Array Width	E1		8.00 BSC	
Overall Length	D		10.00 BSC	
Array Length	D1		8.00 BSC	
Contact Diameter	b		0.40 TYP	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
3. The outer rows and colums of balls are located with respect to datums A and B.

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W